

1/9

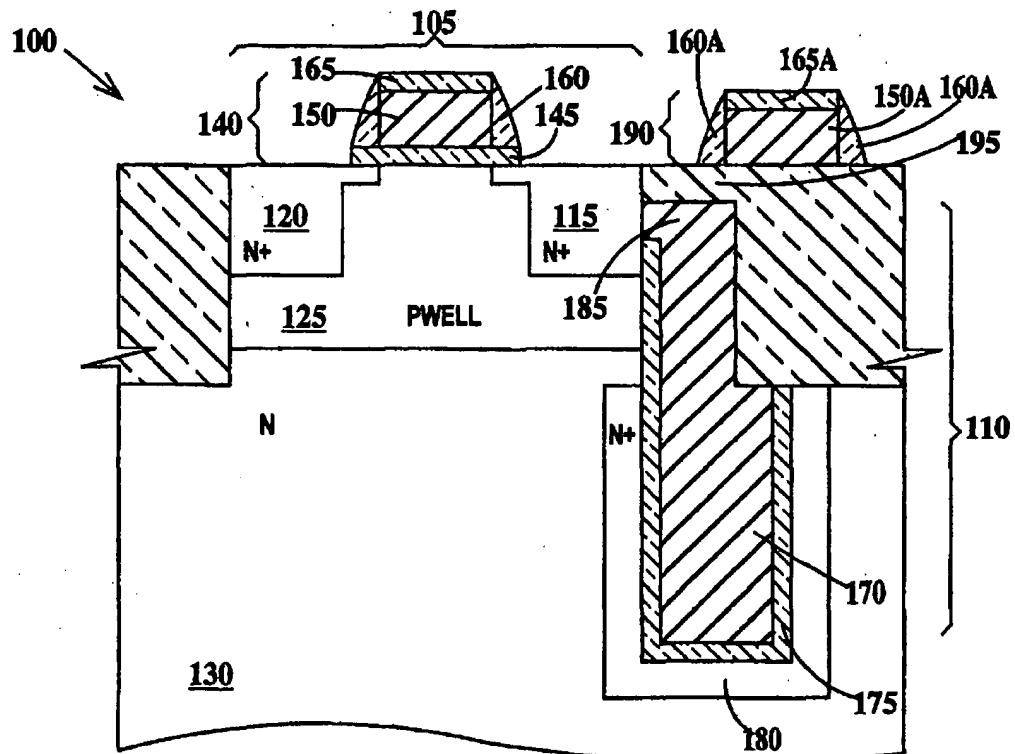


FIG. 1

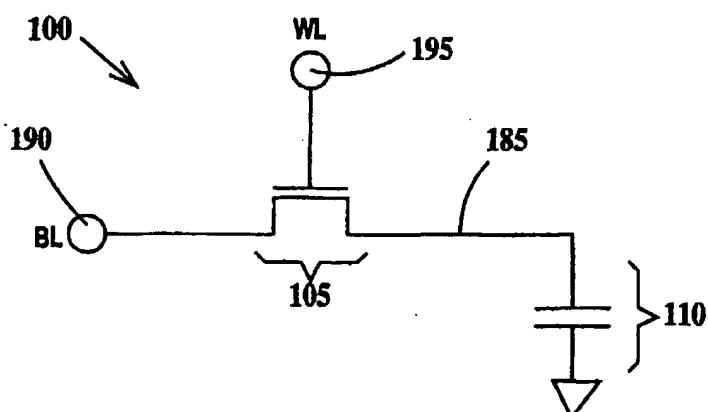
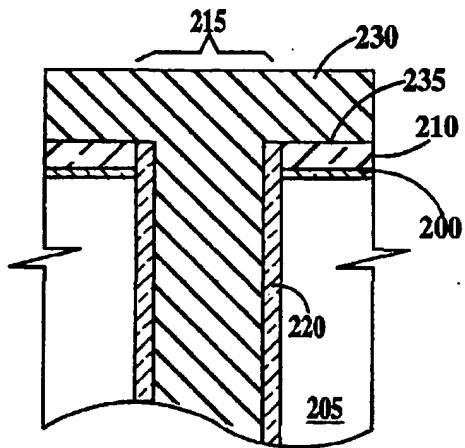
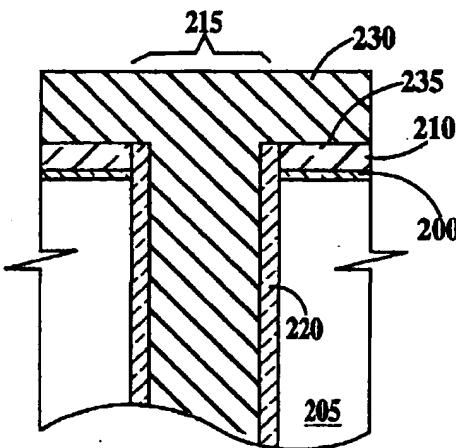
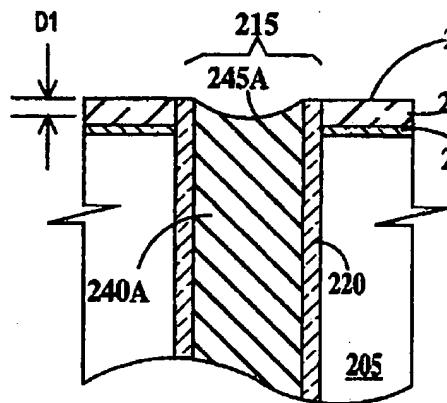
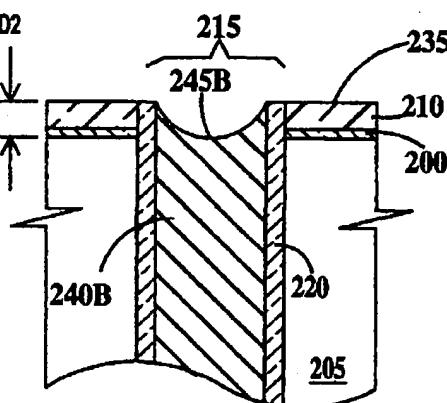
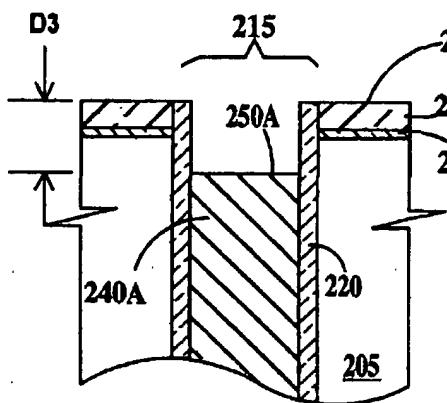
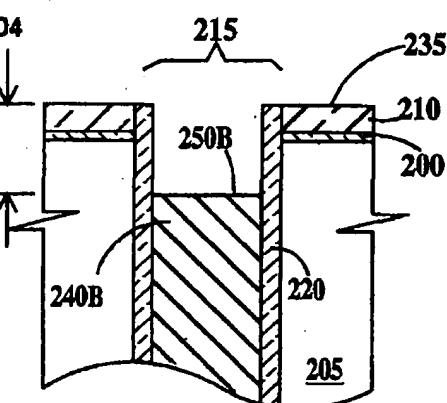
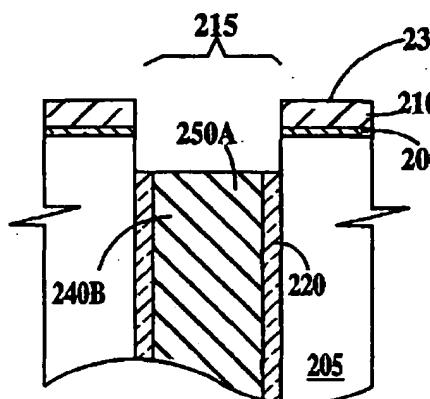
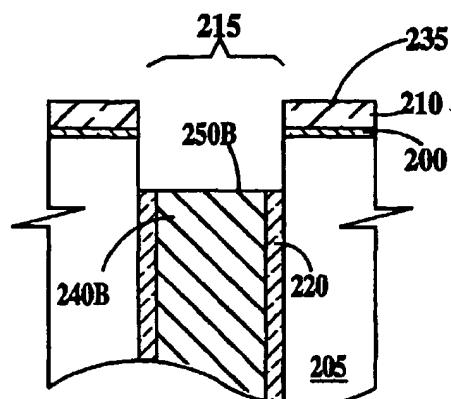
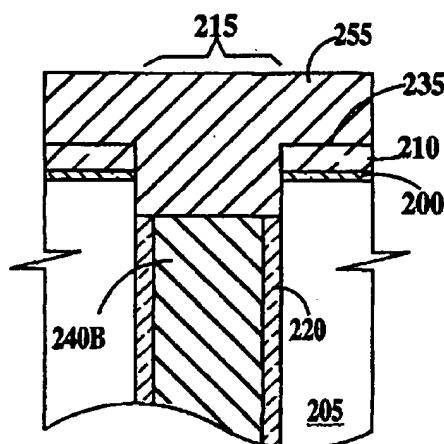
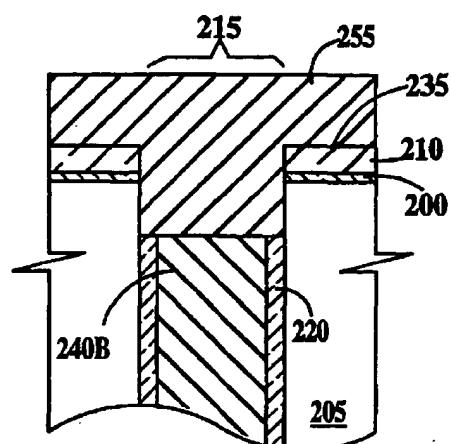
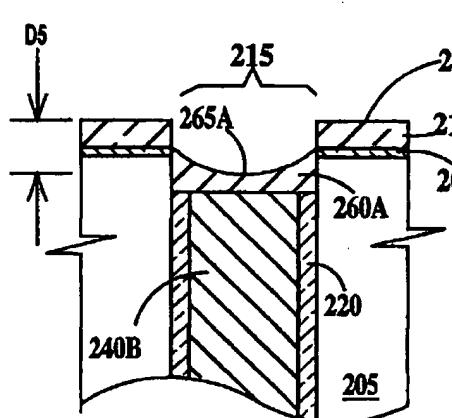
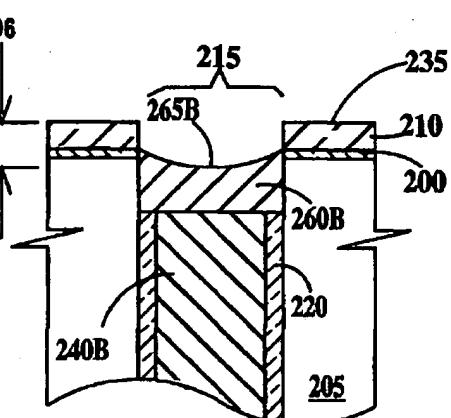


FIG. 2

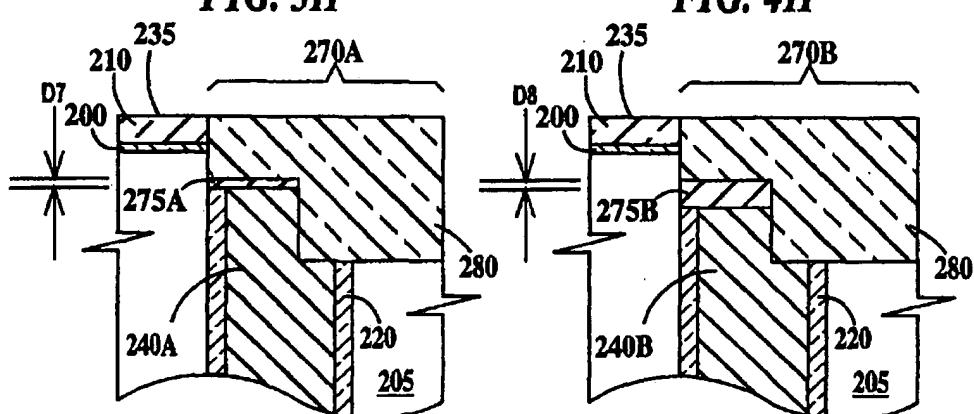
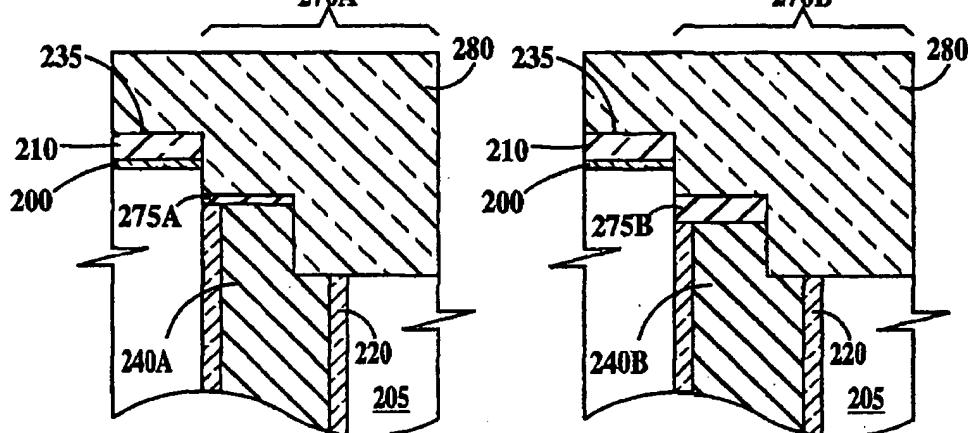
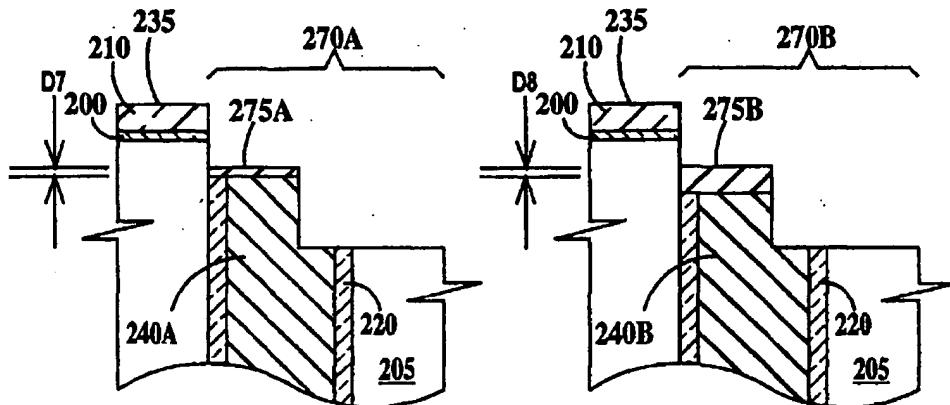
2/9

**FIG. 3A****FIG. 4A****FIG. 3B****FIG. 4B****FIG. 3C****FIG. 4C**

3/9

**FIG. 3D****FIG. 4D****FIG. 3E****FIG. 4E****FIG. 3F****FIG. 4F**

4/9



5/9

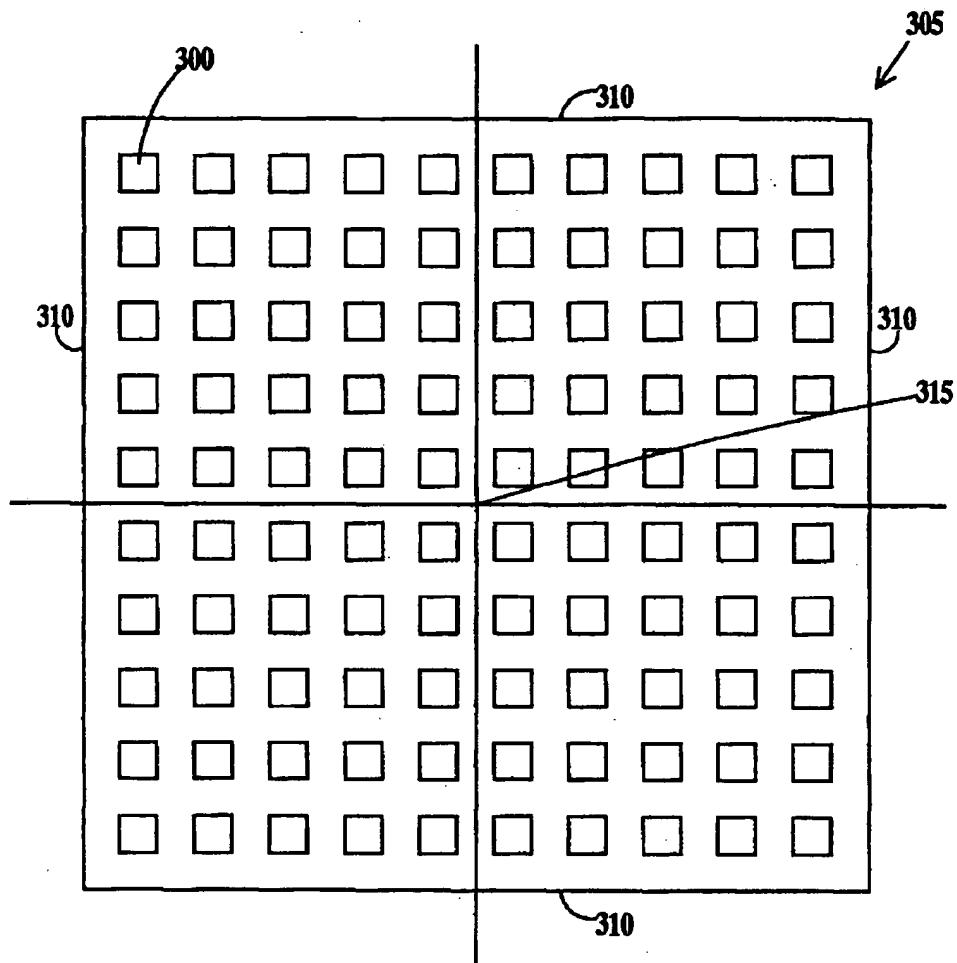


FIG. 5

6/9

**PAD NITRIDE THICKNESS
vs.
DISTANCE FROM EDGE OF ARRAY**

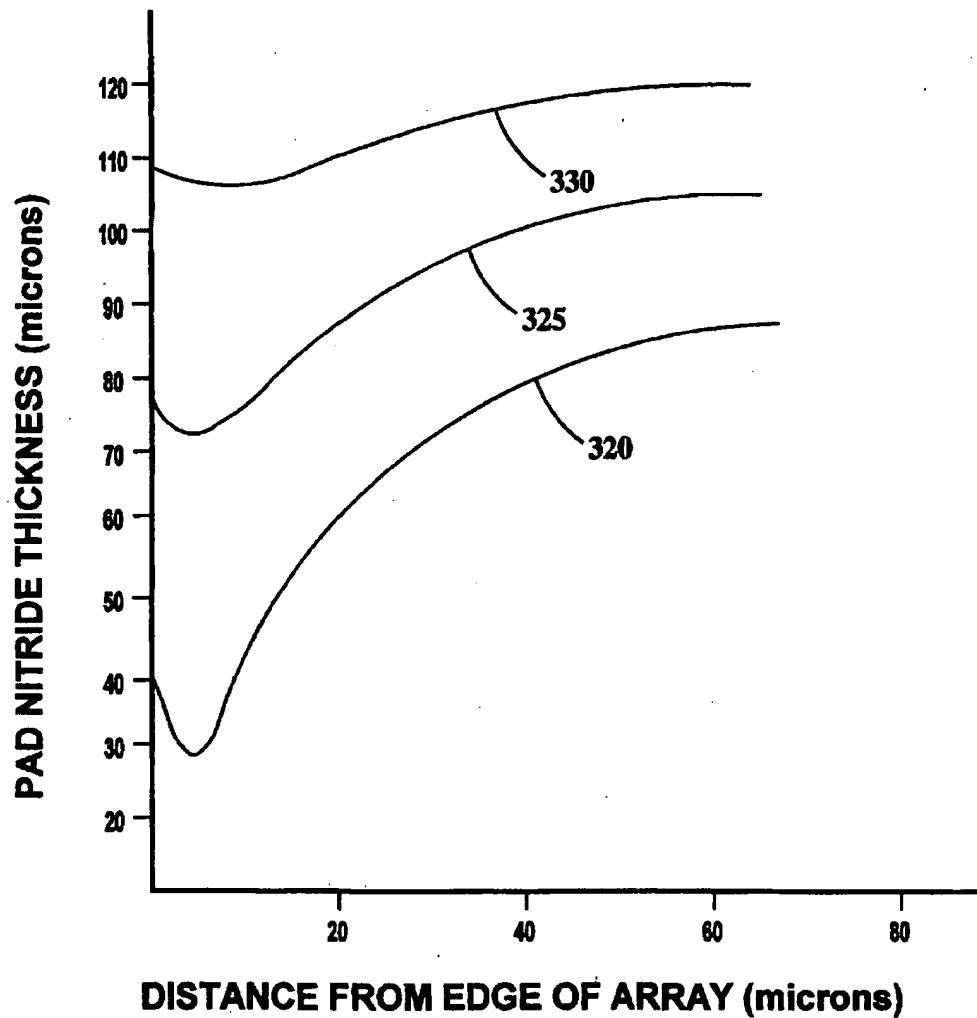


FIG. 6

7/9

**PAD NITRIDE THICKNESS
vs.
POLYSILICON RECESS DEPTH**

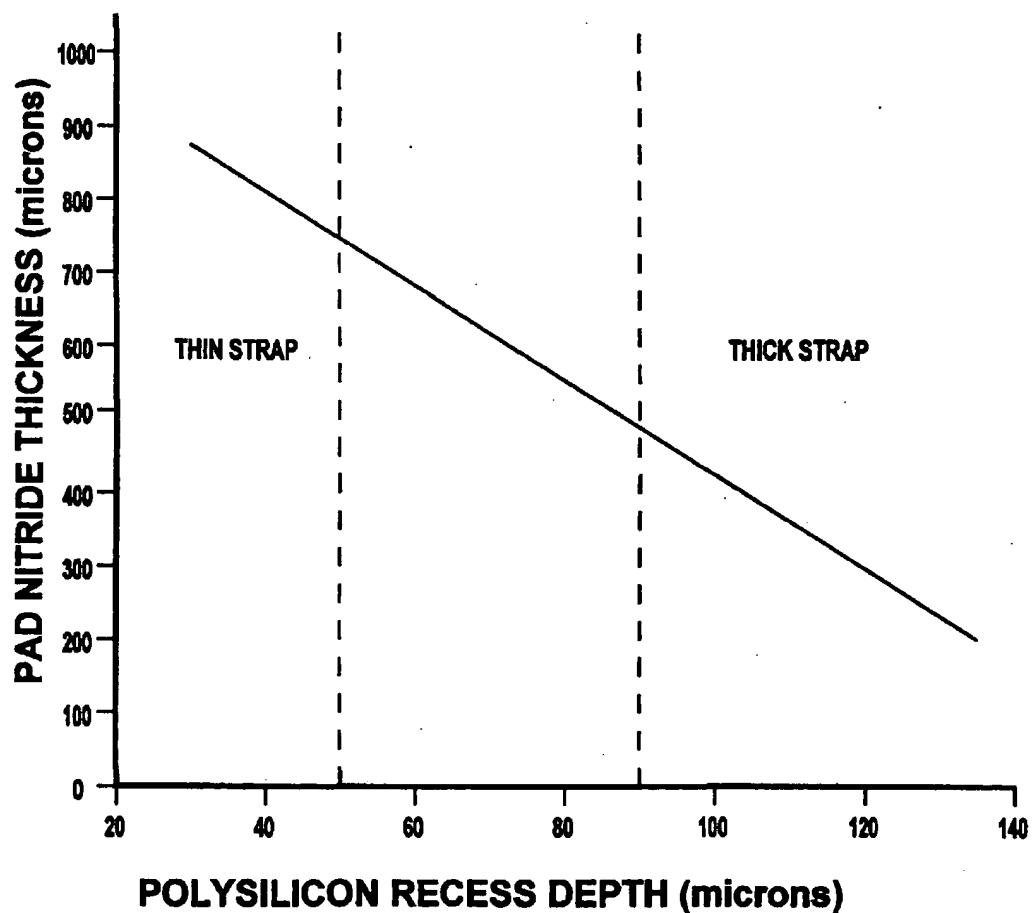


FIG. 7

BUR920040108US1

8/9

**CMP TEMPERATURE
vs.
POLYSILICON DISHING**

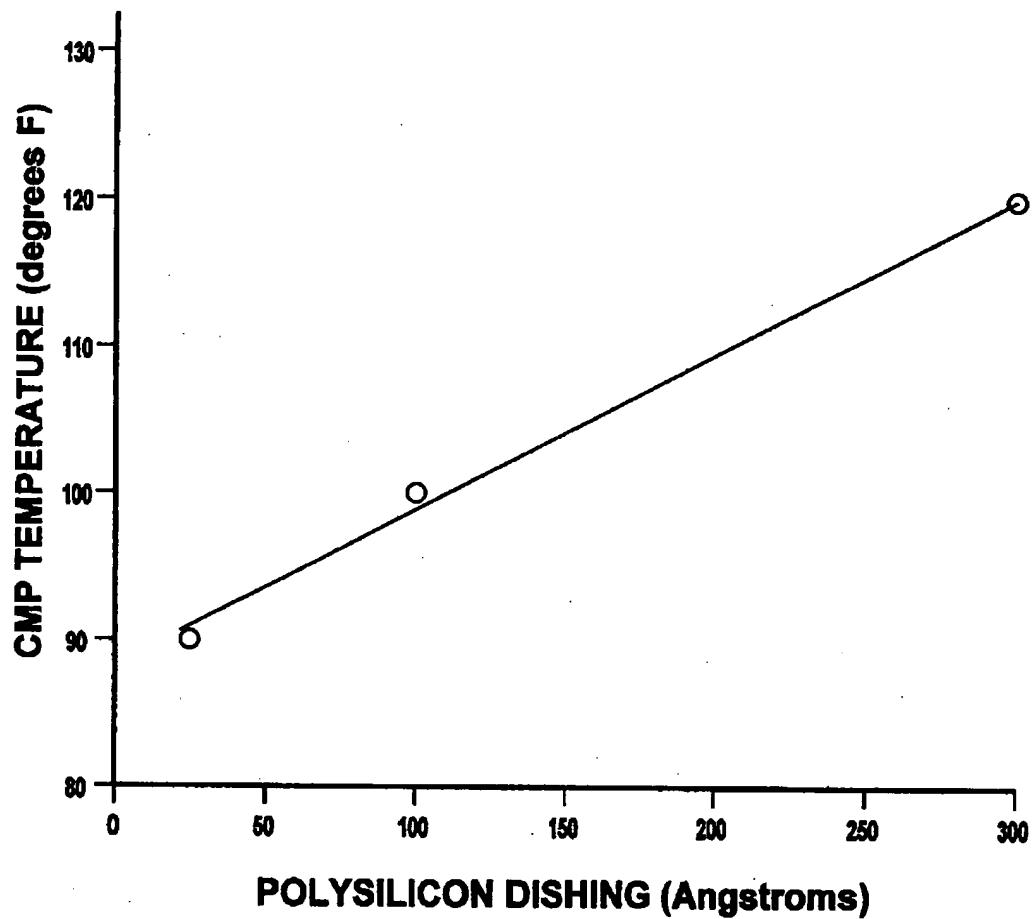


FIG. 8

9/9

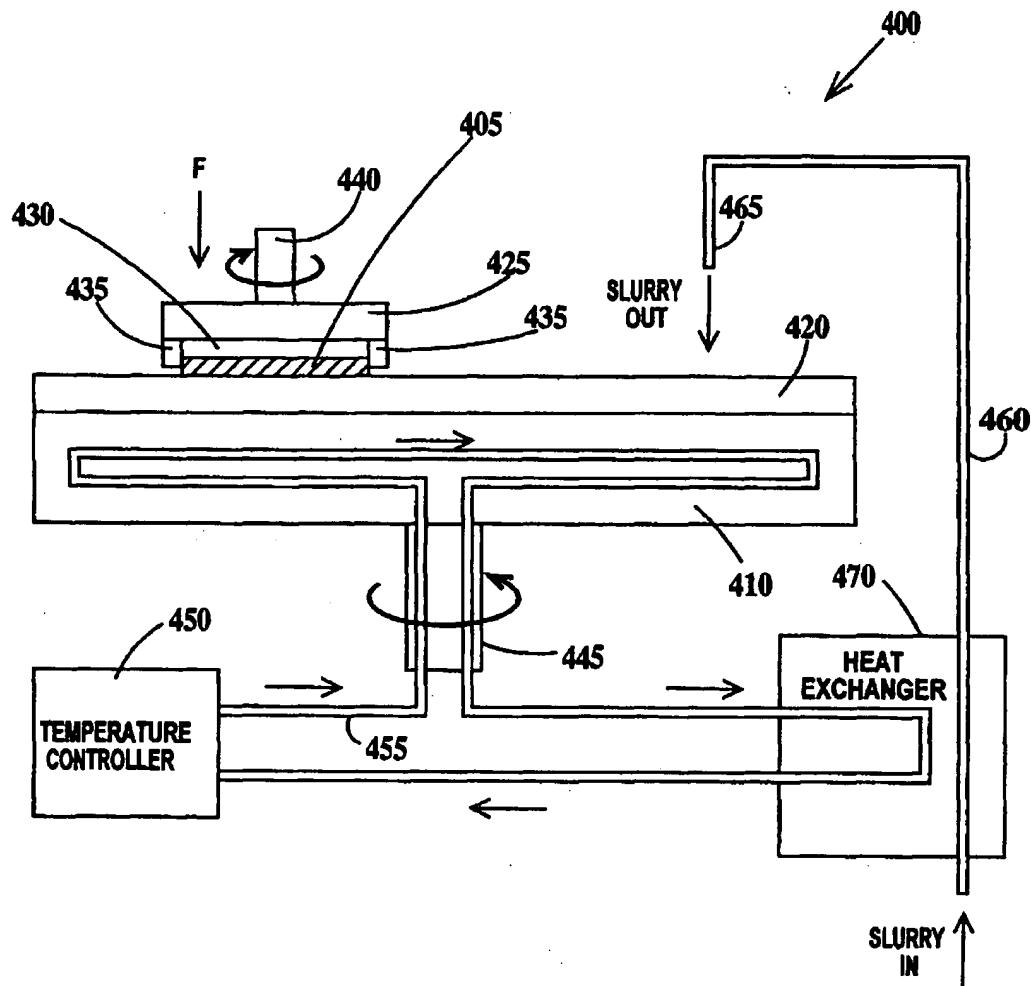


FIG. 9